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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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EPCDESIGNTOOL_XL-EM

Mechanical Die for Electromigration Testing

EPCDESIGNTOOL_XL-EM are sized equivalent to EPC family of devices [EPC2020](#), [EPC2021](#), [EPC2022](#), [EPC2023](#), [EPC2024](#) with die size 6.1 mm x 2.3 mm.

These devices have internal metal layers shorted for electromigration reliability testing.

Figure 1: Die Photo for EPCDESIGNTOOL_XL-EM

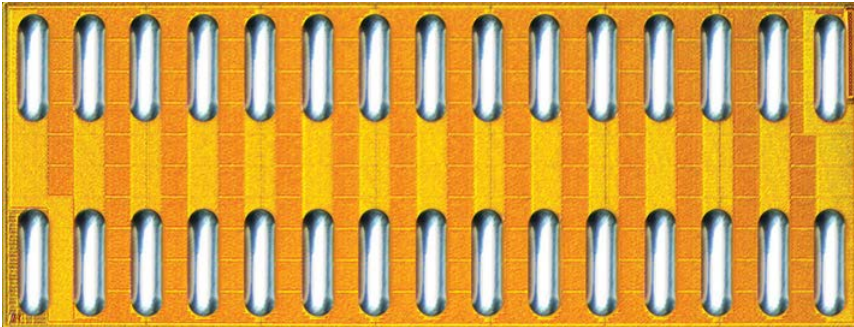
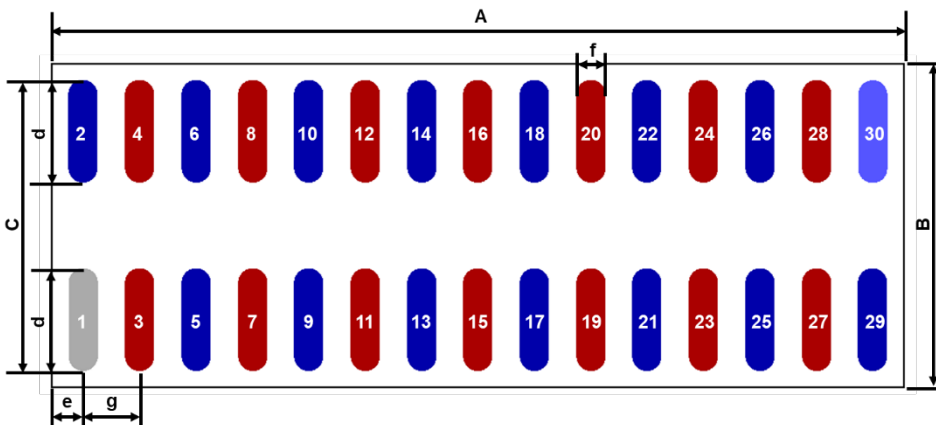


Figure 2: Die Outline (Solder Bar View)



DIM	MICROMETERS		
	MIN	Nominal	MAX
A	6020	6050	6080
B	2270	2300	2330
c	2047	2050	2053
d	717	720	723
e	210	225	240
f	195	200	205
g	400	400	400

Pad 1 is Gate;

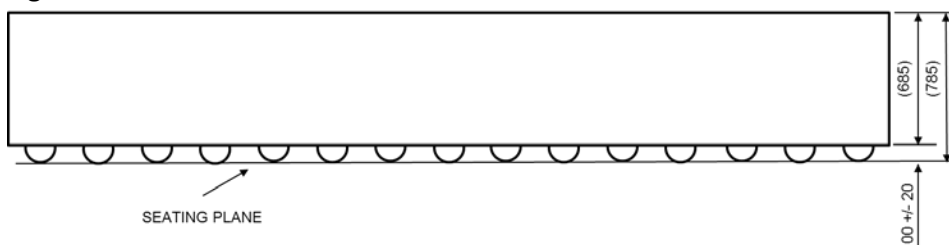
Pads 2, 5, 6, 9, 10, 13, 14, 17, 18, 21, 22, 25, 26, 29 are Source

Pads 3, 4, 7, 8, 11, 12, 15, 16, 19, 20, 23, 24, 27, 28 are Drain

Pad 30 is Substrate

NOTE: Drain and Source are internally shorted at Metal 1 to create a metal resistor

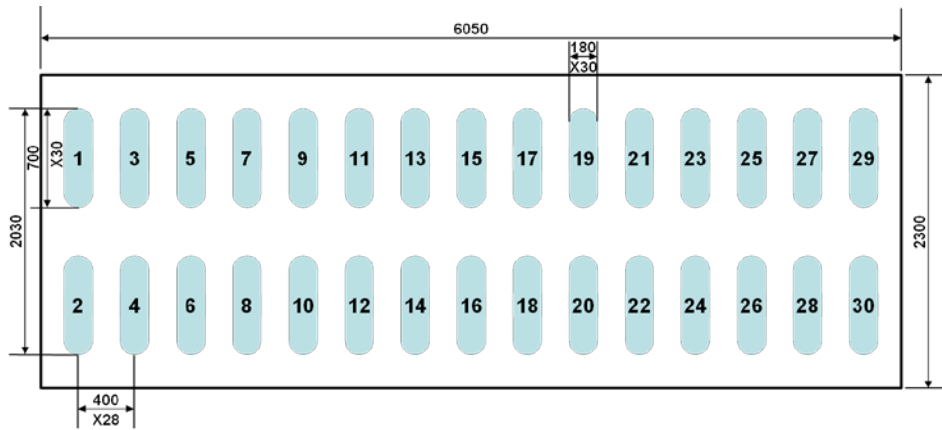
Figure 3: Side View



EPCDESIGNTOOL_XL-EM

Mechanical Die for Electromigration Testing

Figure 4: Recommended Land Pattern (units in μm)



Land pattern is solder mask defined
 Solder mask opening is 180 μm
 It is recommended to have on-Cu trace PCB vias

Pads 1 is Gate;

Pads 2, 5, 6, 9, 10, 13, 14, 17, 18, 21, 22, 25, 26, 29 are Source

Pads 3, 4, 7, 8, 11, 12, 15, 16, 19, 20, 23, 24, 27, 28 are Drain

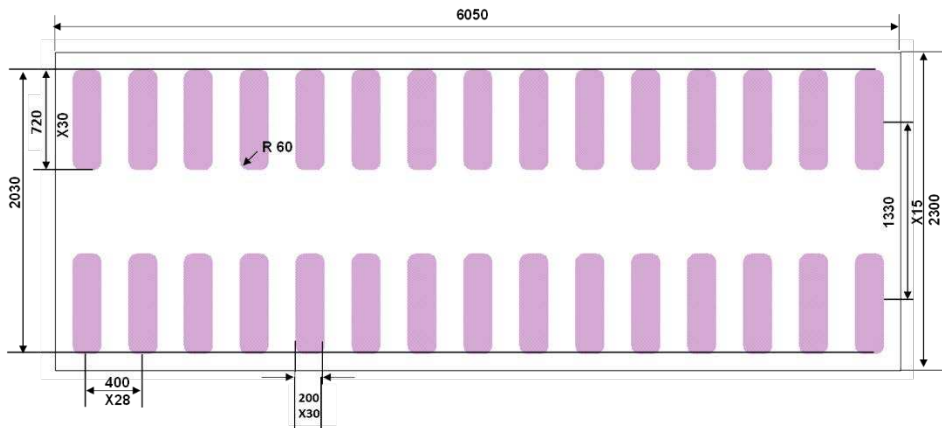
Pad 30 is Substrate

Figure 5: Recommended Stencil Pattern (units in μm)

Intended for use with SAC305 Type 3 solder.

Recommended stencil should be 4mil (100 μm) thick, must be laser cut, openings per drawing.

Additional assembly resources available at epc-co.com/epc/DesignSupport/AssemblyBasics.aspx



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EPC Patent Listing: epc-co.com/epc/AboutEPC/Patents.aspx

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